

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	10/624601.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 11:08
S2	431	(imperfect adj connection) or (discontinued adj areas)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 13:33
S3	1	S1 and S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 14:55
S4	239	345/206.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 11:21
S5	10	takenaka-yuuichi.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 12:19
S7	5855714	gap or hole or (imperfect near connection) or space	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 12:21
S8	265369	S6 and S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:20
S9	82	S8 and S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 12:28
S10	419089	resin and conduct\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 12:28

S11	23	S9 and S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 12:58
S12	186826	thermal near (expansion or expanding or expand)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 12:59
S13	8	S12 and S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 13:00
S14	2	S11 and S12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 13:08
S15	1517	349/158.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 13:08
S16	270	S15 and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 13:19
S17	1372	349/155.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 13:20
S18	303	S17 and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 13:20
S19	7	S2 and "349".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 13:33

S20	52081	insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 14:55
S21	1	S1 and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 14:57
S22	5855714	gap or hole or (imperfect near connection) or space	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:21
S23	573394	(insulat\$3 near3 (substrate or layer or part))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:20
S24	265369	S22 and S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:20
S25	6076752	gap or hole or (imperfect near connection) or space or slit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:21
S26	269060	S25 and S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:21
S27	1517	349/158.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:22
S28	188	S26 and S27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:39
			US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB			

S29	253878	PCB or (printed adj circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:40
S30	18476	S29 and S25 and S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:40
S31	961	349/84.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:40
S32	1	S30 and S31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:41
S33	1372	349/155.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:41
S34	11	S30 and S33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:41
S35	239	345/206.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:07
S36	961	349/84.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:07
S37	1373	349/155.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:07
			US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB			

S38	1517	349/158.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:20
S39	1137	349/138.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:20
S40	5856777	gap or hole or (imperfect near connection) or space	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 15:54
S41	609	S39 and S40	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:20
S42	253972	PCB or (printed adj circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:32
S43	58501	S40 same S42	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:33
S44	8	S43 and S39	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:42
S45	377	349/142.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 14:16
S46	327	349/150.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:45

S47	2	S43 and S45	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:46
S48	53	S43 and S46	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:46
S50	271	349/151.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 09:35
S51	253972	PCB or (printed adj circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 15:59
S52	158030	resin same (conductive or conductor or conducting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 15:41
S53	5146	S52 same S51	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 15:42
S54	37745	"349".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 15:42
S55	51	S53 and S54	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 15:42
S56	6834033	gap or hole or (imperfect near connection) or space or slot or slit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 15:54
			US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB			

S57	5613	(multi-layered or (multi adj layered) or (multiple adj layered) or multi-layer or (multi adj layer) or (multiple adj layer)) with S51	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 15:56
S58	1669	S56 same S57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 15:57
S59	11	S54 and S58	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 15:57
S60	132994	S51 and S56	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 15:59
S61	1037	S60 and S54	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 16:00
S62	117	S61 and S52	USPAT	OR	ON	2005/11/15 16:06
S63	370557	Sharp Kabushiki Kaisha.As.	USPAT	OR	ON	2005/11/15 16:18
S64	53433	S63 and slot	USPAT	OR	ON	2005/11/15 16:18
S65	80	S63 and S58	USPAT	OR	ON	2005/11/15 16:19
S66	2	S65 and "349".clas.	USPAT	OR	ON	2005/11/15 16:20
S67	79838	thermal adj expans\$5	USPAT	OR	ON	2005/11/15 16:33
S68	14320	"349".clas.	USPAT	OR	ON	2005/11/15 16:20
S69	544	S67 and S68	USPAT	OR	ON	2005/11/15 16:20
S70	466	S69 and S56	USPAT	OR	ON	2005/11/15 16:22
S71	137	S67 and S52 and S57 and S56	USPAT	OR	ON	2005/11/15 16:34
S72	7	("4506004" "4715117" "4728568" "5591353" "6272745" "6276055" "6631838").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/15 16:36
S73	253972	PCB or (printed adj circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 08:18

S74	158030	resin same (conductive or conductor or conducting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 08:18
S75	6834033	gap or hole or (imperfect near connection) or space or slot or slit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:44
S76	5613	(multi-layered or (multi adj layered) or (multiple adj layered) or multi-layer or (multi adj layer) or (multiple adj layer)) with S73	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:09
S77	79838	thermal adj expan\$5	USPAT	OR	ON	2005/11/16 08:18
S78	137	S77 and S74 and S76 and S75	USPAT	OR	ON	2005/11/16 10:35
S79	21608	TCP or (tape adj carrier adj package) or T-C-P	USPAT	OR	ON	2005/11/16 08:25
S80	5	S74 and S76 and S75 and S77 and S79	USPAT	OR	ON	2005/11/16 08:28
S81	239	345/206.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 13:23
S82	8	S81 and S77	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 08:27
S83	9	S74 and S76 and S75 and S79	USPAT	OR	ON	2005/11/16 08:28
S84	271	349/151.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 09:55
S85	424	349/152.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 10:03
S86	5764619	hannstar display corp.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 10:03

S87	17	S86 and S78	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 10:17
S89	1	09/204130.app.	USPAT	OR	ON	2005/11/16 10:19
S90	53	("3913219" "3947956" "4416914" "4555745" "4566186" "4632845" "4774634" "4808434" "4870746" "5225969" "5298687" "5305523" "5347258" "5354599" "5384434" "5428190" "5502889" "5527998" "5599595" "5688584" "5716663" "5727310" "5747222" "5758575" "5763058" "5814366").PN. OR ("6021050").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/16 10:21
S91	2990	428/209.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/16 10:26
S92	19	S91 and S78	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/16 10:21
S93	1065	428/194.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/16 10:26
S94	3741037	S75	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/16 10:26
S95	503	S75 and S93	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/16 10:31
S96	2	09/136201.app.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/16 10:31
S97	4	S78 and "349".clas.	USPAT	OR	ON	2005/11/16 10:37
S98	54	S79 and (prevent\$3 with S77)	USPAT	OR	ON	2005/11/16 10:46
S99	3236	438/106.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 10:48
S100	59	S99 and S76 and S75	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 10:49

S101	86	multiplelayer or multiplelayering with S73	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:10
S102	48	S101 and S75	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:26
S103	14007	prevent\$3 same S77	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:26
S104	11222	S103 and S75	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:32
S105	64	S104 and S76	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:27
S106	4584231	(imperfect near connection) or space or slot or slit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:44
S107	2530	S76 and S106	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:44
S108	491	S107 and S74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:45
S109	573537	(insulat\$3 near3 (substrate or layer or part))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 12:30

S110	119	S109 and S79 and S77	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 12:30
S111	239	345/206.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 13:18
S112	1	"6738123".pn. and insulat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 13:24
S113	2	("6738123").URPN.	USPAT	OR	ON	2005/11/16 13:24
S114	6	("5745202" "5969780" "6198051" "6198521" "6369867" "6573954").PN. OR ("6870589").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/16 13:31
S115	52097	insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 13:35
S116	7	S115 and S79 and S76 and S75	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 13:38
S117	18	("6121553").URPN.	USPAT	OR	ON	2005/11/16 14:22
S118	1	S116 and (semiconductor adj chip)	USPAT	OR	ON	2005/11/16 14:23
S119	0	10/624601.app.	USPAT	OR	ON	2005/11/16 14:24
S120	1	10/624601.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 14:24
S121	1	S120 and (semiconductor adj chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 14:33
S122	1	resin and 09/204130.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 14:33